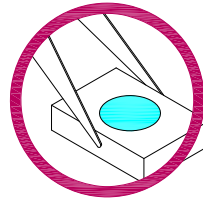


Handling Precautions

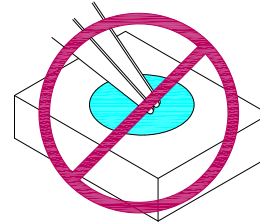
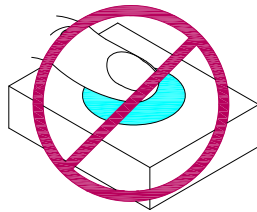
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

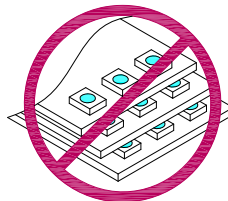
1. Handle the component along the side surfaces by using forceps or appropriate tools.



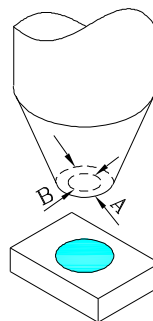
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



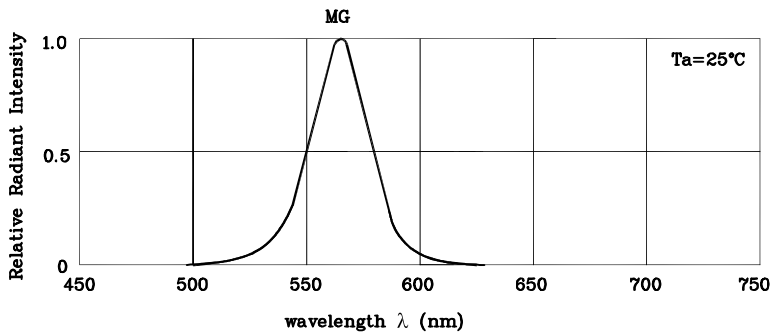
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



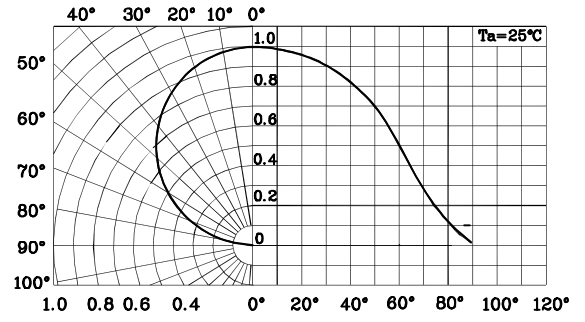
- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

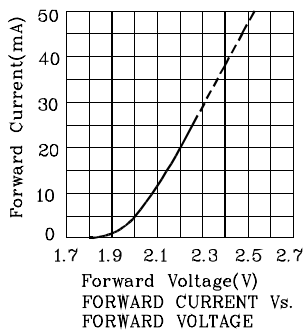


RELATIVE INTENSITY Vs. CIE WAVELENGTH

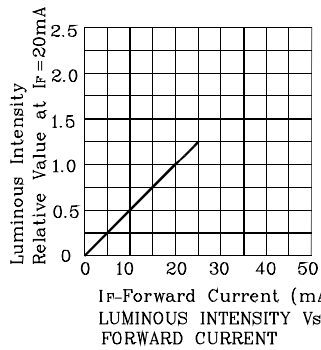


SPATIAL DISTRIBUTION

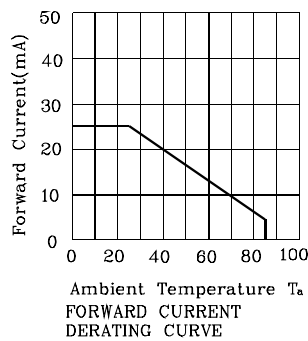
❖ MG



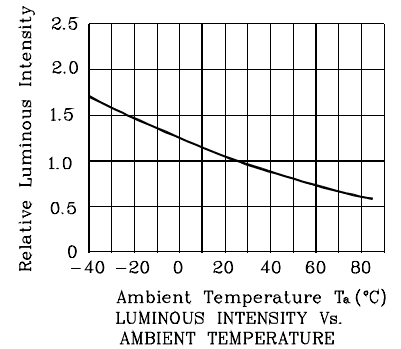
FORWARD CURRENT(V)
FORWARD CURRENT Vs.
FORWARD VOLTAGE



If=Forward Current (mA)
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



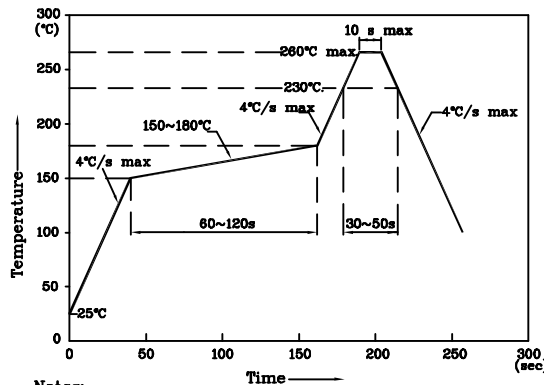
Ambient Temperature T_a (°C)
FORWARD CURRENT
DERATING CURVE



Ambient Temperature T_a (°C)
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)



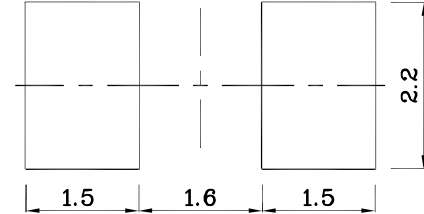
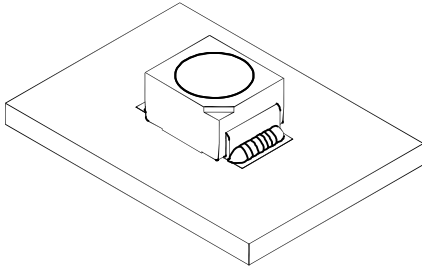
Notes:

1. Maximum soldering temperature should not exceed 280°C
2. Recommended reflow temperature: 145°C-260°C
3. Do not put stress to the epoxy resin during high temperatures conditions

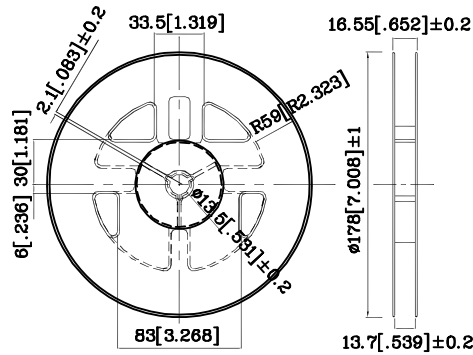


❖ The device has a single mounting surface.
The device must be mounted according to the specifications.

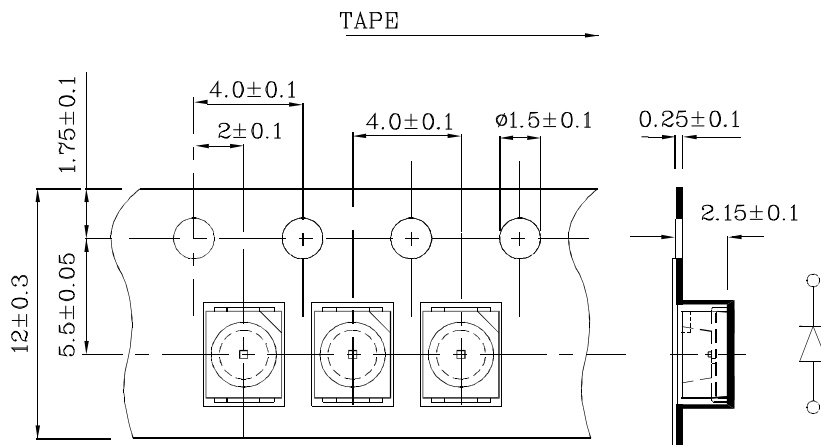
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units : mm)



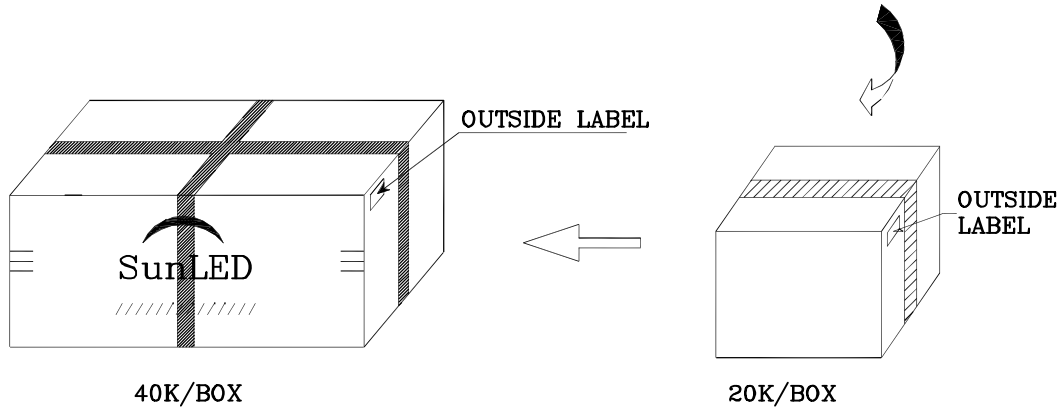
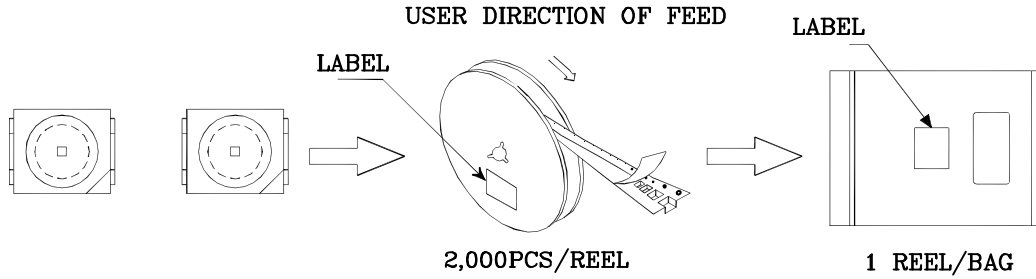

Remarks:

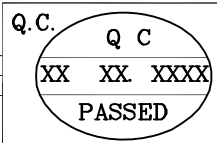

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: ± 1 nm
2. Luminous intensity / luminous flux: $\pm 15\%$
3. Forward Voltage: ± 0.1 V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

	
P/NO : XZxxx45x	
QTY : 2,000 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	